

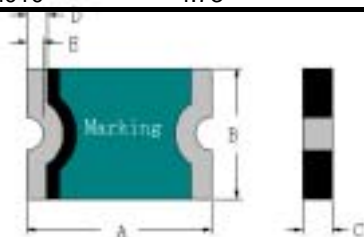
Features

- Small size of 1812
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency Recognition: UL、CSA、TUV



Product Dimensions (mm)

Part number	A	B	C	D	E
	Max.	Max.	Max.	Max.	Min.
LP-MSM010	4.73	3.41	0.81	0.60	0.30



Top View

Side View

Part Marking System

W ——— Product family



————— Current rating

Electrical Characteristics

Part number	I_H	I_T	V_{max}	I_{max}	T_{trip}	$P_{d\,typ}$	R_{min}	R_{1max}
	(A)	(A)	(V)	(A)	Current(A) Time(S)	(W)	()	()
LP-MSM010	0.10	0.20	60	10	1.5 0.15	1.0	0.70	6.00

I_H =Hold current: maximum current at which the device will not trip at 25 °C still air.

I_T =Trip current: minimum current at which the device will always trip at 25 °C still air.

V_{max} =Maximum voltage device can withstand without damage at rated current.

I_{max} =Maximum fault current device can withstand without damage at rated voltage.

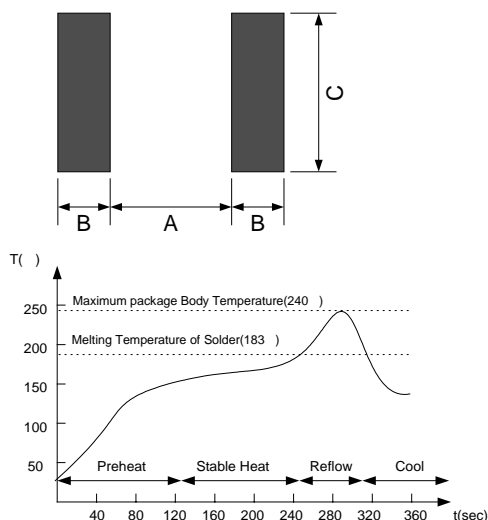
T_{trip} =Maximum time to trip(s) at assigned current.

$P_{d\,typ}$ =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min} =Minimum device resistance at 25 °C prior to tripping.

R_{1max} =Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A	B	C
	(mm)	(mm)	(mm)
LP-MSM010	3.45	1.78	3.15

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 2000pcs per reel.